

**AMENDMENTS TO THE CLAIMS**

**Please cancel claims 1-6 and add the following new claims 7-12.**

**LISTING OF CLAIMS:**

- [7] (new) A protection film for a thin film device formed on a substrate, which comprises a hydrogen content of not less than 30 at%.
- [8] (new) A protection film according to Claim 7, wherein the protection film is one of SiN, SiO, SiON, SiC or SiCN type or diamond like carbon (DLC).
- [9] (new) An organic electroluminescent device which comprises at least a first electrode, an organic luminescent layer, and a second electrode formed on a substrate, wherein the organic electroluminescent device further comprises a protection film which covers the organic electroluminescent device and of which hydrogen content is not less than 30at%.
- [10] (new) An organic electroluminescent device according to Claim 9, wherein the protection film is one of SiN, SiO, SiON, SiC or SiCN type or diamond like carbon (DLC).
- [11] (new) A process for manufacturing an organic electroluminescent device which comprises at least a first electrode, an organic luminescent layer, and an second electrode formed on a substrate, which comprises forming a protection film which covers the organic electroluminescent device, wherein hydrogen content of the protection film is not less than 30at% through the use of CVD method or sputtering method.
- [12] (new) A process according to Claim 11, wherein the CVD method is plasma CVD method.